

## P-channel 20 V, 0.087 $\Omega$ typ., 3 A STripFET™ H7 Power MOSFET in a SOT23-6L package

Datasheet - production data

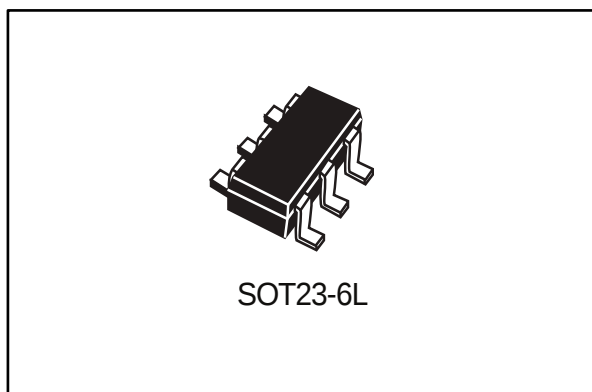
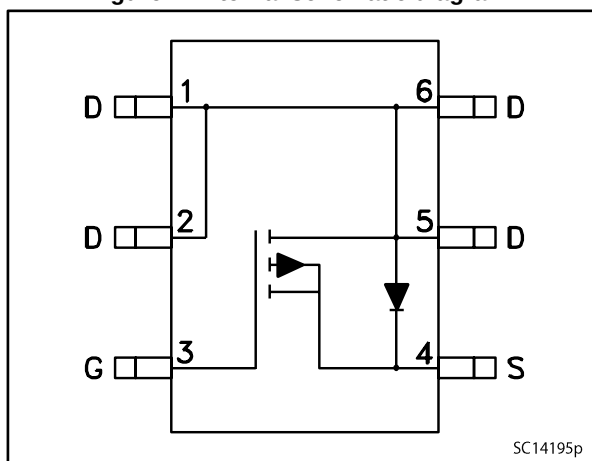


Figure 1: Internal schematic diagram



### Features

| Order code | V <sub>DS</sub> | R <sub>DS(on)</sub> max | I <sub>D</sub> |
|------------|-----------------|-------------------------|----------------|
| STT3P2UH7  | 20 V            | 0.1 $\Omega$ @ 4.5      | 3 A            |

- Very low on-resistance
- Very low capacitance and gate charge
- High avalanche ruggedness

### Applications

- Switching applications

### Description

This P-channel Power MOSFET utilizes the STripFET H7 technology with a trench gate structure combined with extremely low on-resistance. The device also offers ultra-low capacitances for higher switching frequency operations.

Table 1: Device summary

| Order code | Marking | Package  | Packaging     |
|------------|---------|----------|---------------|
| STT3P2UH7  | 3L2U    | SOT23-6L | Tape and reel |



For the P-channel Power MOSFET, current and voltage polarities are reversed.

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# 1 Electrical ratings

Table 2: Absolute maximum ratings

| Symbol         | Parameter                                                             | Value       | Unit               |
|----------------|-----------------------------------------------------------------------|-------------|--------------------|
| $V_{DS}$       | Drain-source voltage                                                  | 20          | V                  |
| $V_{GS}$       | Gate-source voltage                                                   | $\pm 8$     | V                  |
| $I_D$          | Drain current (continuous) at $T_{pcb} = 25\text{ }^{\circ}\text{C}$  | 3           | A                  |
| $I_D$          | Drain current (continuous) at $T_{pcb} = 100\text{ }^{\circ}\text{C}$ | 1.9         | A                  |
| $I_{DM}^{(1)}$ | Drain current (pulsed)                                                | 12          | A                  |
| $P_{TOT}$      | Total dissipation at $T_{pcb} = 25\text{ }^{\circ}\text{C}$           | 1.6         | W                  |
| $T_{stg}$      | Storage temperature range                                             | - 55 to 150 | $^{\circ}\text{C}$ |
| $T_j$          | Operating junction temperature range                                  |             |                    |

**Notes:**

<sup>(1)</sup>Pulse width limited by safe operating area

Table 3: Thermal data

| Symbol              | Parameter                                             | Value | Unit                        |
|---------------------|-------------------------------------------------------|-------|-----------------------------|
| $R_{thj-pcb}^{(1)}$ | Thermal resistance junction-pcb max, single operation | 78    | $^{\circ}\text{C}/\text{W}$ |

**Notes:**

<sup>(1)</sup>When mounted on 1inch<sup>2</sup> FR-4 board, 2 oz Cu



For the P-channel Power MOSFET, current and voltage polarities are reversed.

## 2 Electrical characteristics

(T<sub>C</sub> = 25 °C unless otherwise specified)

Table 4: On /off states

| Symbol               | Parameter                         | Test conditions                                             | Min. | Typ.  | Max. | Unit |
|----------------------|-----------------------------------|-------------------------------------------------------------|------|-------|------|------|
| V <sub>(BR)DSS</sub> | Drain-source breakdown voltage    | I <sub>D</sub> = 250 μA, V <sub>GS</sub> = 0                | 20   |       |      | V    |
| I <sub>DSS</sub>     | Zero gate voltage drain current   | V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0                 |      |       | 1    | μA   |
| I <sub>GSS</sub>     | Gate-body leakage current         | V <sub>GS</sub> = ± 8 V, V <sub>DS</sub> = 0                |      |       | 10   | nA   |
| V <sub>GS(th)</sub>  | Gate threshold voltage            | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA | 0.4  |       | 1    | V    |
| R <sub>DS(on)</sub>  | Static drain-source on-resistance | V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 1.5 A             |      | 0.087 | 0.1  | Ω    |
|                      |                                   | V <sub>GS</sub> = 2.5 V, I <sub>D</sub> = 1.5 A             |      | 0.11  | 0.13 | Ω    |
|                      |                                   | V <sub>GS</sub> = 1.8 V, I <sub>D</sub> = 1.5 A             |      | 0.145 | 0.18 | Ω    |

Table 5: Dynamic

| Symbol           | Parameter                    | Test conditions                                                                                                                          | Min. | Typ. | Max. | Unit |
|------------------|------------------------------|------------------------------------------------------------------------------------------------------------------------------------------|------|------|------|------|
| C <sub>iss</sub> | Input capacitance            | V <sub>DS</sub> = 10 V, f = 1 MHz,<br>V <sub>GS</sub> = 0                                                                                | -    | 510  | -    | pF   |
| C <sub>oss</sub> | Output capacitance           |                                                                                                                                          | -    | 66   | -    | pF   |
| C <sub>rss</sub> | Reverse transfer capacitance |                                                                                                                                          | -    | 44   | -    | pF   |
| Q <sub>g</sub>   | Total gate charge            | V <sub>DD</sub> = 10 V, I <sub>D</sub> = 3 A,<br>V <sub>GS</sub> = 4.5 V<br>(see <a href="#">Figure 14: "Gate charge test circuit"</a> ) | -    | 4.8  | -    | nC   |
| Q <sub>gs</sub>  | Gate-source charge           |                                                                                                                                          | -    | 0.7  | -    | nC   |
| Q <sub>gd</sub>  | Gate-drain charge            |                                                                                                                                          | -    | 0.8  | -    | nC   |

Table 6: Switching times

| Symbol              | Parameter           | Test conditions                                                                                                                                                                                              | Min. | Typ. | Max | Unit |
|---------------------|---------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|------|-----|------|
| t <sub>d(on)</sub>  | Turn-on delay time  | V <sub>DD</sub> = 10 V, I <sub>D</sub> = 1.5 A,<br>R <sub>G</sub> = 4.7 Ω, V <sub>GS</sub> = 4.5 V<br>(see <a href="#">Figure 15: "Test circuit for inductive load switching and diode recovery times"</a> ) | -    | 9    | -   | ns   |
| t <sub>r</sub>      | Rise time           |                                                                                                                                                                                                              | -    | 21   | -   | ns   |
| t <sub>d(off)</sub> | Turn-off delay time |                                                                                                                                                                                                              | -    | 40   | -   | ns   |
| t <sub>f</sub>      | Fall time           |                                                                                                                                                                                                              | -    | 19   | -   | ns   |



For the P-channel Power MOSFET, current and voltage polarities are reversed.

Table 7: Source drain diode

| Symbol         | Parameter                | Test conditions                                                                                                                                                                                                                  | Min. | Typ. | Max. | Unit |
|----------------|--------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|------|------|------|
| $V_{SD}^{(1)}$ | Forward on voltage       | $I_{SD} = 1\text{ A}$ , $V_{GS} = 0$                                                                                                                                                                                             | -    | -    | 1    | V    |
| $t_{rr}$       | Reverse recovery time    | $V_{DD} = 10\text{ V}$<br>$di/dt = 100\text{ A}/\mu\text{s}$ , $I_{SD} = 1\text{ A}$<br>$T_j = 150\text{ }^\circ\text{C}$ (see <a href="#">Figure 15: "Test circuit for inductive load switching and diode recovery times"</a> ) | -    | 12.5 |      | ns   |
| $Q_{rr}$       | Reverse recovery charge  |                                                                                                                                                                                                                                  | -    | 5    |      | nC   |
| $I_{RRM}$      | Reverse recovery current |                                                                                                                                                                                                                                  | -    | 0.8  |      | A    |

**Notes:**

<sup>(1)</sup>Pulsed: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.



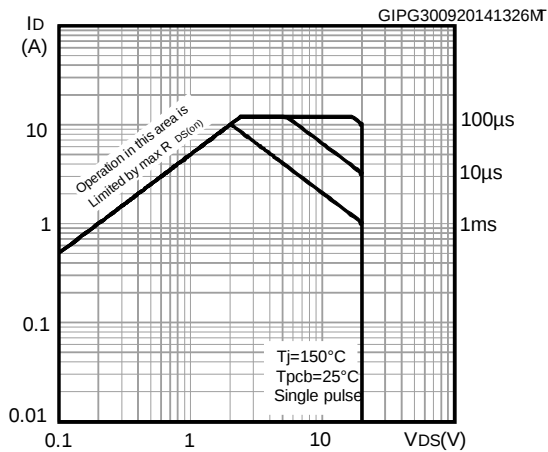
For the P-channel Power MOSFET, current and voltage polarities are reversed.

## 2.1 Electrical characteristics (curves)

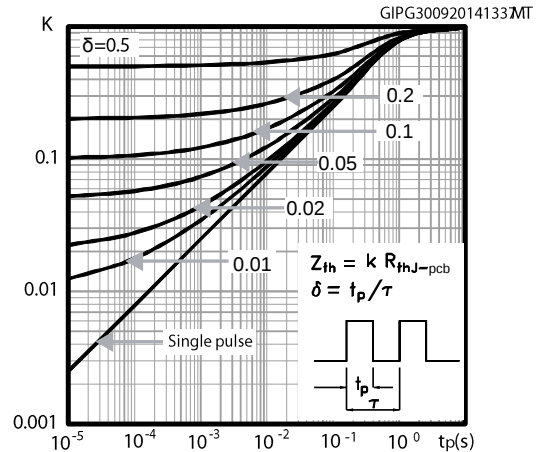


For the P-channel Power MOSFET, current and voltage polarities are reversed.

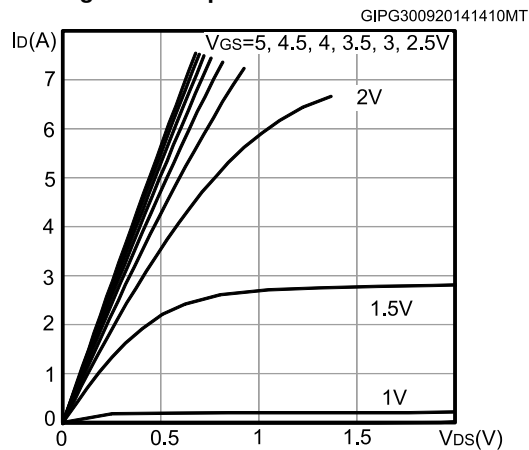
**Figure 2: Safe operating area**



**Figure 3: Thermal impedance**



**Figure 4: Output characteristics**



**Figure 5: Transfer characteristics**

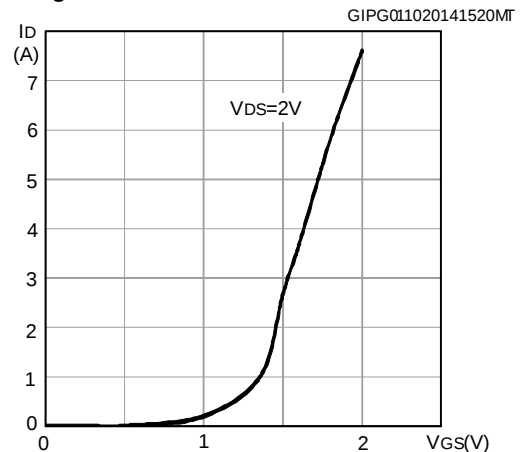


Figure 6: Gate charge vs gate-source voltage

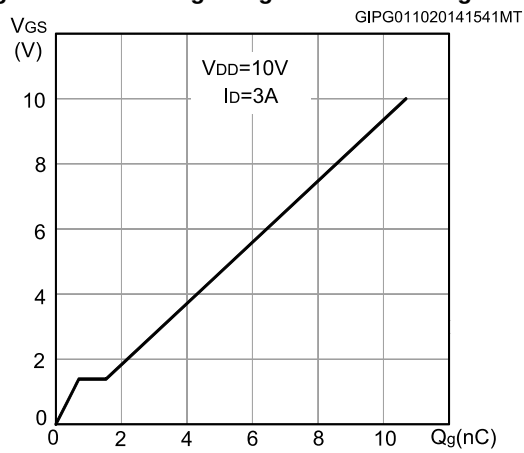


Figure 7: Static drain-source on-resistance

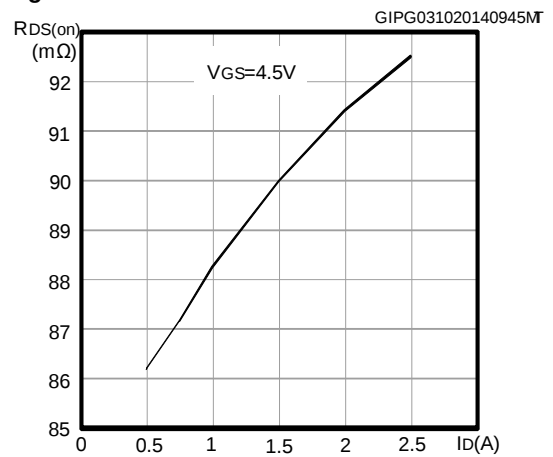


Figure 8: Capacitance variations

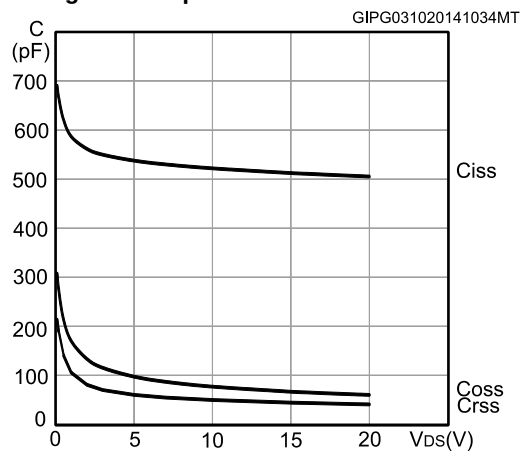


Figure 9: Normalized gate threshold voltage vs temperature

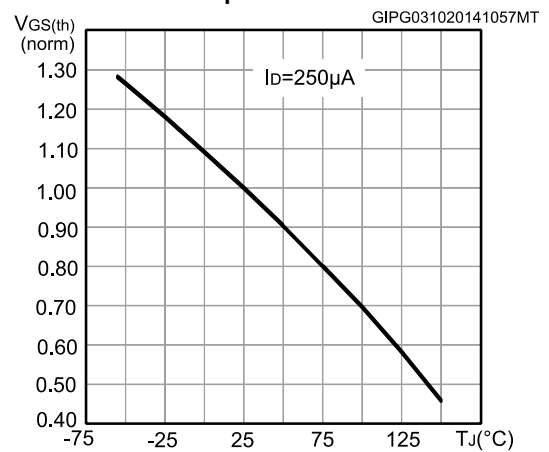


Figure 10: Normalized on-resistance vs temperature

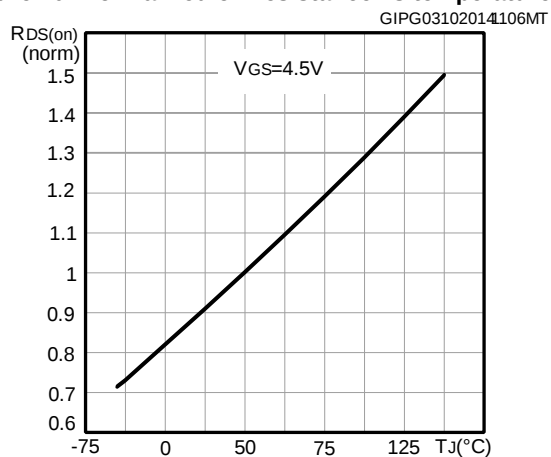


Figure 11: Normalized V(BR)DSS vs temperature

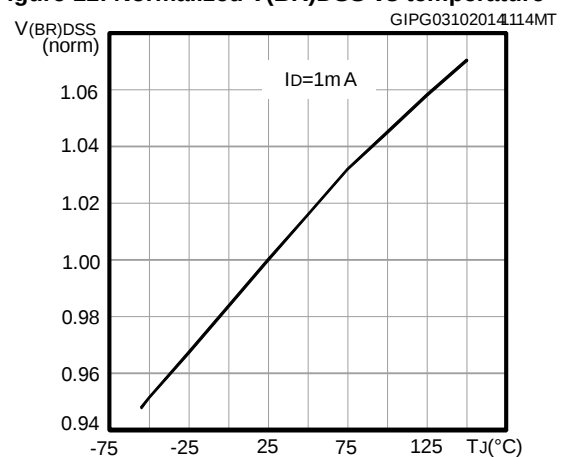
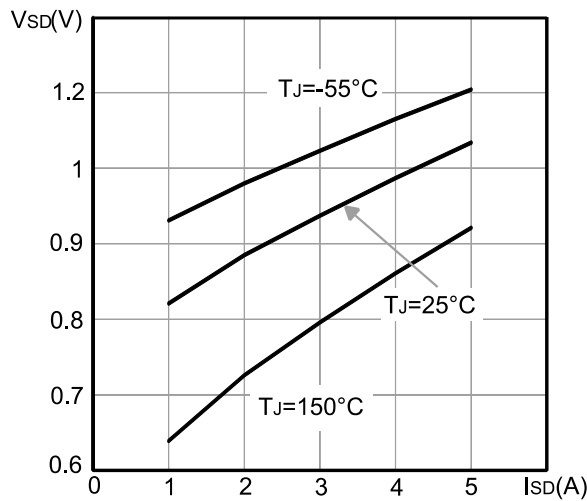


Figure 12: Source-drain diode forward characteristics

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### 3 Test circuits

Figure 13: Switching times test circuit for resistive load

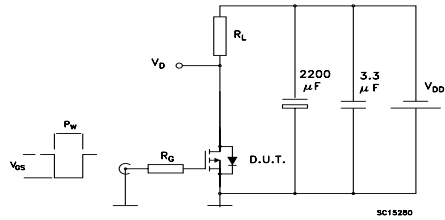


Figure 14: Gate charge test circuit

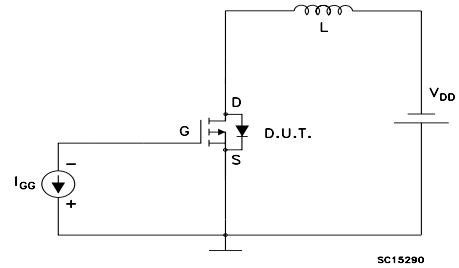
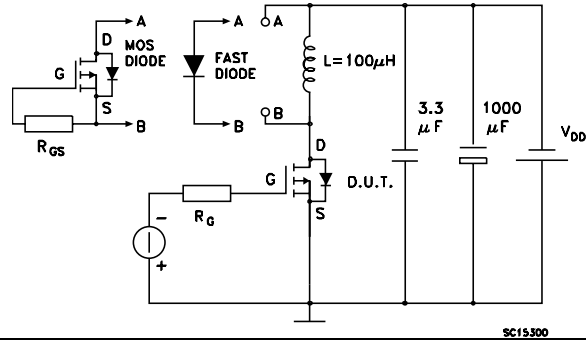


Figure 15: Test circuit for inductive load switching and diode recovery times



## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK® is an ST trademark.

### 4.1 SOT23-6L package mechanical data

Figure 16: SOT23-6L package drawing

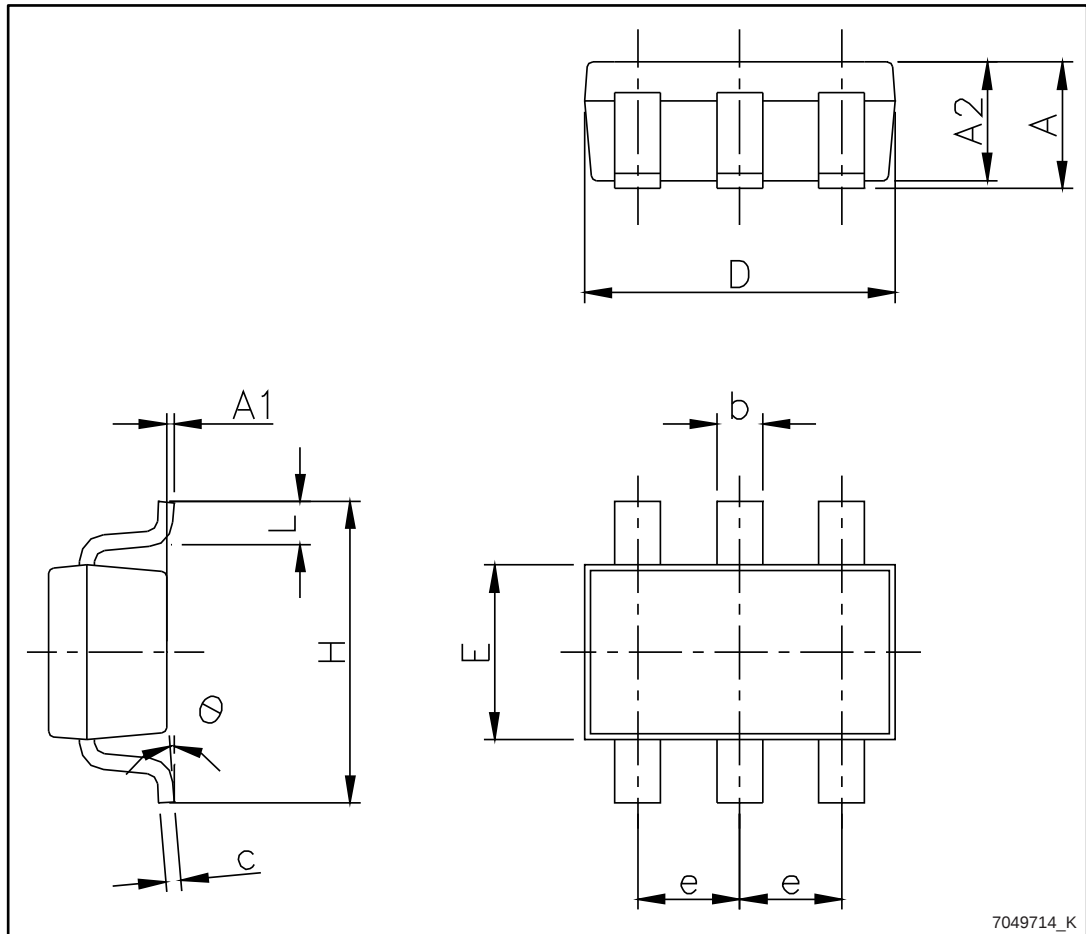
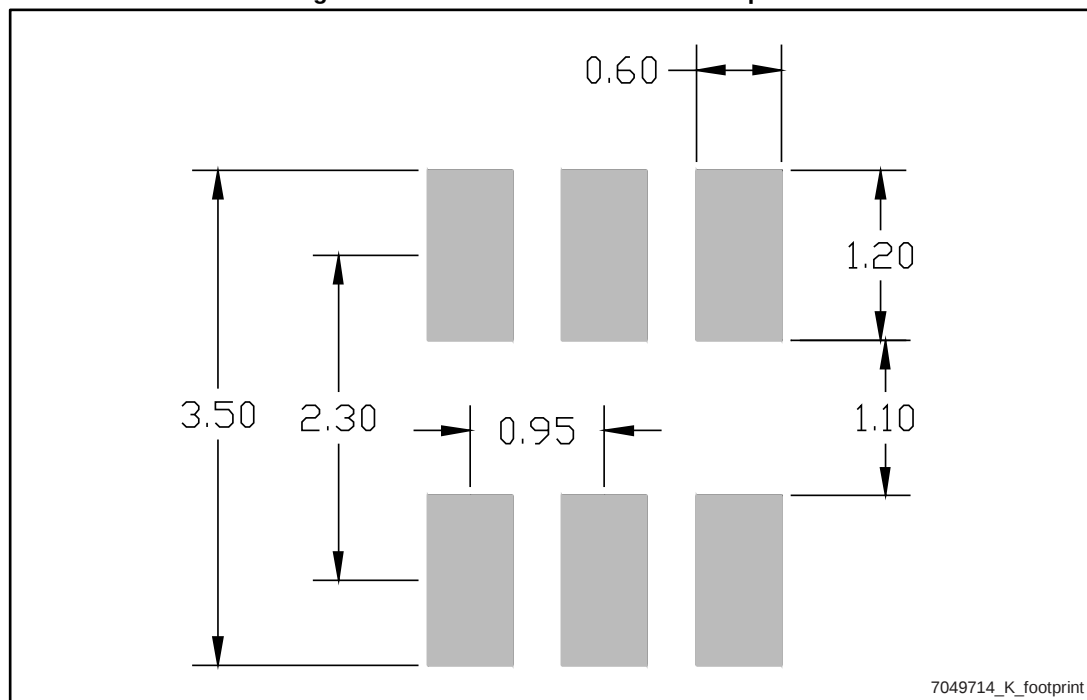


Table 8: SOT23-6L package mechanical data

| Dim.     | mm    |       |       |
|----------|-------|-------|-------|
|          | Min.  | Typ.  | Max.  |
| A        |       |       | 1.25  |
| A1       | 0.00  |       | 0.15  |
| A2       | 1.00  | 1.10  | 1.20  |
| b        | 0.36  |       | 0.50  |
| C        | 0.14  |       | 0.20  |
| D        | 2.826 | 2.926 | 3.026 |
| E        | 1.526 | 1.626 | 1.726 |
| e        | 0.90  | 0.95  | 1.00  |
| H        | 2.60  | 2.80  | 3.00  |
| L        | 0.35  | 0.45  | 0.60  |
| $\theta$ | 0°    |       | 8°    |

Figure 17: SOT23-6L recommended footprint



## 5 Revision history

**Table 9: Document revision history**

| Date        | Revision | Changes                                                                                                                                                                                                                                                            |
|-------------|----------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 18-Jul-2013 | 1        | First release.                                                                                                                                                                                                                                                     |
| 03-Oct-2014 | 2        | Document status promoted from target data to production data.<br>Updated title, features and description in cover page. Updated <i>Section 2: "Electrical characteristics"</i> and <i>Section 4.1: "SOT23-6L package mechanical data"</i> .<br>Minor text changes. |
| 12-Sep-2016 | 3        | Updated <a href="#">Table 2: "Absolute maximum ratings"</a> .<br>Minor text changes.                                                                                                                                                                               |

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